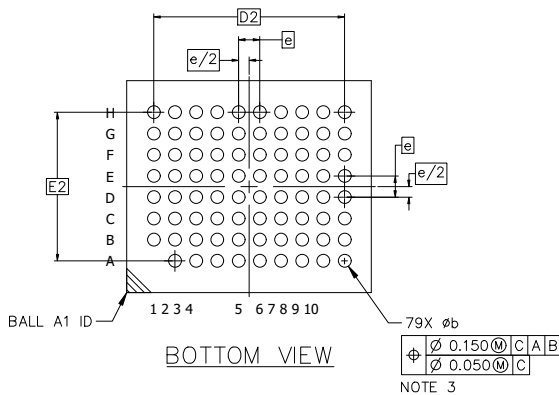
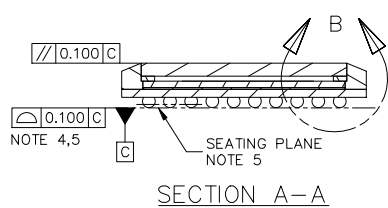
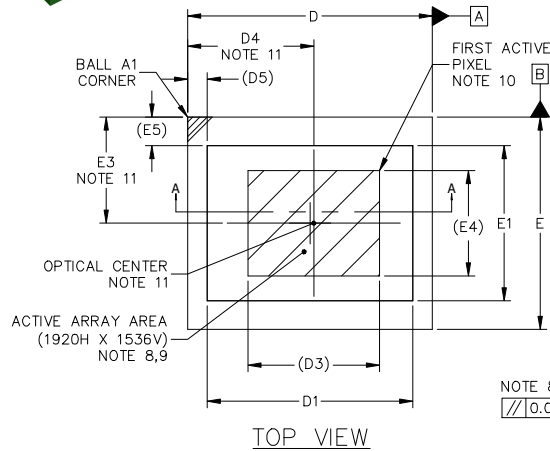
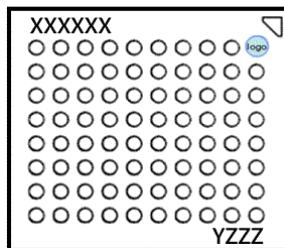


IBGA79 7.50x6.50x1.05, 0.65P
CASE 503CS
ISSUE B

DATE 07 FEB 2024



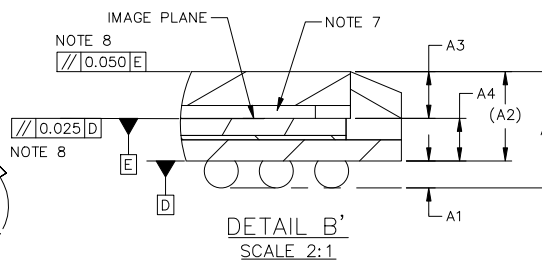
GENERIC
MARKING DIAGRAM*



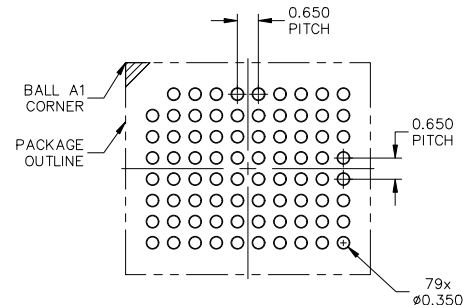
XXXX = Specific Device Code
Y = Year
ZZZ = Lot Traceability

NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52; AR COATING R<1% 420-850nm (EACH SIDE).
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.150 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS $\pm 0.5^\circ$.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.115, 0.000)
12. PACKAGE CENTER (X, Y) = (0.000, 0.000).



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	1.550
A1	0.270	0.320	0.370
A2	1.050 REF.		
A3	0.500	0.550	0.600
A4	0.450	0.500	0.550
b	0.350	0.400	0.450
D	7.425	7.500	7.575
D1	6.200	6.300	6.400
D2	5.850 BSC		
D3	4.032 REF.		
D4	3.790	3.865	3.940
D5	0.600 REF.		
E	6.425	6.500	6.575
E1	4.660	4.760	4.860
E2	4.550 BSC		
E3	3.175	3.250	3.325
E4	3.226 REF.		
E5	0.870 REF.		
e	0.650 BSC		



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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